WHAT IS CLAIMED IS:

1. A power distribution system comprising:

a first printed circuit board;

a second printed circuit board mounted on the first printed circuit board;

a power supply mounted on the first printed circuit board;

a processor mounted on the second printed circuit board; and

a flexible connector comprising a first end electrically connected to the processor and a second end electrically connected to the power supply and configured with a length so that the power supply is in a spaced relationship relative to the processor, the flexible connector including a plurality of stacked layers arranged generally parallel to each other for distributed power transmission including:

at least two ground layers; and

at least one power layer,

wherein the power layer is sandwiched between two of the at least two ground layers.

2. The system of claim 1 wherein the second printed circuit board comprises:

a capacitive coupler including a plurality of capacitors, wherein the first end of the flexible connector is electrically connected to the second printed circuit board via the capacitive coupler; and

wherein the second end of the flexible connector is connected directly to the power supply.

3. The system of claim 1 and further comprising:

a chassis that is removably electrically connected to the first printed circuit board and on which the power supply is mounted and comprising a bus through which the power supply is electrically connected to the second end of the flexible connector.

4. The system of claim 1 and further comprising:

at least one signal layer,

wherein the signal layer is separated from the at least one power layer by one of the at least two ground layers.

5. The system of claim 4 wherein the flexible connector comprises the signal layer is disposed between two of the at least two ground layers and is separated from the at least one power layer by at least one of the at least two ground layers.

6. The system of claim 4 wherein the flexible connector comprises the signal layer disposed as an outside layer adjacent only one ground layer of the at least two ground layers.

7. The system of claim 1 wherein the flexible connector comprises at least one of a flexible circuitry cable and a flexible circuitry board, wherein the flexible connector comprises a resilient and malleable material.

8. The system of claim 1 wherein flexible connector is physically spaced from a surface of the first printed circuit board.

9. A power distribution connector for a processor, the connector comprising:

a flexible circuitry member comprising a first end configured for electrical connecting to a processor and a second end configured for electrical connecting to a power supply, and having a length to maintain a distance between the first end and the second end, and comprising a plurality of stacked layers arranged generally parallel to each other including:

a plurality of ground layers;

at least one power layer; and

wherein the at least one power layer is interposed between at least two of the plurality of ground layers.

10. A power transmission connector comprising:

means for transmitting power to a power supply and a processor including means for distributing the power between a plurality of ground planes and power planes arranged for minimizing a an inductance loop between the power supply and the processor.

11. The connector of claim 10 wherein the means for transmitting power comprises a flexible circuitry board comprising a first end electrically connected to the processor and a second end electrically connected to the power supply and configured with a length to separate the power supply from the processor, and means for distributing the power comprises arranging the ground planes and the power planes generally parallel to each other so that at least one power plane is sandwiched between a pair of ground planes.

12. A method of transmitting power between a power supply and a processor, the method comprising:

separating the power supply and the processor to have a fixed spaced distance relative to each other; and

connecting the power supply to the processor in a low inductance relationship via a flexible, resilient circuitry member having a plurality of sandwiched layers including at least one power layer and a plurality of return ground layers so that each at least one power layer has at least one return ground layer and the at least one power layer is interposed between at least two of the plurality of return ground layers.

13. The method of claim 12 wherein connecting the power supply to the processor further comprises:

arranging the flexible circuitry member to include at least one signal layer.

14. The method of claim 12 wherein separating the power supply from the processor comprises:

disposing the power supply on a chassis; and

disposing the processor on a circuit card that is removably insertable into the chassis.

15. The method of claim 14 wherein connecting the power supply and the processor comprises:

electrically and mechanically connecting the circuit card and the chassis via a bus interface of the circuit card and of the chassis;

connecting a first end of the flexible circuitry member to the processor; and

connecting a second end of the flexible circuitry member to the bus interface of the circuit card.

16. The method of claim 12 wherein separating the power supply from the processor comprises disposing the power supply and the processor on a printed circuit board such that the fixed spaced distance prevents co-location of the power supply and the processor; and

wherein connecting the processor and the power supply to each other comprises:

connecting a first end of the flexible circuitry member to the processor; and

connecting a second end of the flexible circuitry member to the power supply.

17. The method of claim 12 wherein connecting the processor to the power supply comprises:

Electrically connecting the processor to a first printed circuit board via a second printed circuit board; and

electrically connecting a first end of the flexible circuitry member to the second printed circuit board via a capacitive coupler.

18. The method of claim 12 wherein connecting the processor to the power supply via the flexible circuitry member comprises:

Arranging the flexible circuitry member to be independent of the printed circuit board on which the processor and the power supply are mounted.

19. The method of claim 12 wherein connecting the processor to the power supply via the flexible circuitry member comprises:

maintaining the flexible circuitry member in spaced relationship relative to a surface of the printed circuit board.

20. The method of claim 12 wherein separating the processor from the power supply comprises:

arranging the processor and the power supply on a printed circuit board with a circuit element disposed on a surface of the printed circuit board between the power supply and the processor.